

Datasheet

# CFexpress 3TE6 series

- PCIe Gen. III x2, NVMe 1.3
- Excellent data transfer speed
- CFexpress Type B Form-Factor
- Zero mechanical interference
- LDPC ECC engine supported
- End-to-end Data Path Protection
- Support Write Protect Function



## Introduction

Innodisk CFexpress 3TE6 adopts CFexpress Version 1.0 type B Form-Factor. With PCIe interface and TLC NAND Flash, CFexpress 3TE6 supports PCIe Gen III x2 and is compliant with NVM 1.3, providing excellent top and sustained performance. Moreover, it adopts TLC NAND Flash providing high endurance and reliability. With sophisticated error detection and correction (ECC) functions, the module can ensure full End-to-end Data Path Protection that secures the data transmission between host system and NAND Flash.

Innodisk CFexpress 3TE6 is a small and removable memory card providing low latency and extreme speed but with low power consumption. It is ideal for gaming, edge computing and professional digital recording.

# CFexpress 3TE6 series

Contact us for more  
information about the  
CFexpress 3TE6.

Innodisk is a service-driven  
provider of industrial embedded  
flash and DRAM storage products  
and technologies, with a focus on  
the cloud computing,  
industrial/embedded, and  
aerospace and defense industries.

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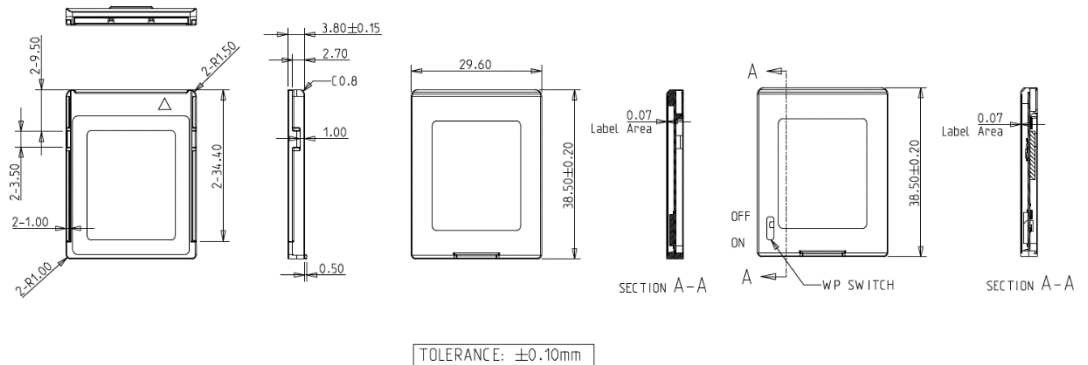
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## Diagram



## Specifications

Interface	PCIe Gen. III x2
Flash Type	3D TLC
P/E cycle	3,000
Capacity	64GB~1TB
Max. Channels	4
Sequential R/W (MB/sec, max.)	2000/1900
Max. Power Consumption(rms)	3.1W
Thermal Sensor	√
External DRAM buffer	-
H/W Write Protect	√(optional)
Dimension (WxLxH)	29.6 X 38.5 X 3.8 mm
Environment	Vibration: 20G @7~2000Hz Shock: 1500G @ 0.5ms Storage Temperature: -40°C ~ +85°C MTBF: 3,000,000

## Ordering Information

Operation Temp.	64GB	128GB	256GB	512GB	1TB
Standard Grade (0°C ~ +70°C)	DECFX- 64GDD1ECADF(W)	DECFX- A28DD1%CAQF(W)	DECFX- B56DD1%CAQF(W)	DECFX- C12DD1%CAQF(W)	DECFX- 01TDD1%CAQF(W)
Industrial Grade (-40°C ~ +85°C)	DECFX- 64GDD1EWADF(W)	DECFX- A28DD1EWAQF(W)	DECFX- B56DD1EWAQF(W)	DECFX- C12DD1EWAQF(W)	DECFX- 01TDD1EWAQF(W)

(W). Optional HW Write Protect

%: E: 64 layers 3D TLC; K: 112 layers 3D TLC